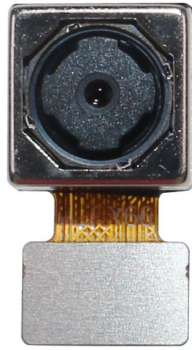
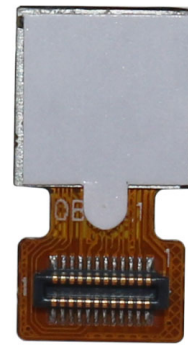


YDS-OV5645-Y660B V3.1

5MP OmniVision OV5645 MIPI Interface Auto Focus Camera Module



Front View



Back View

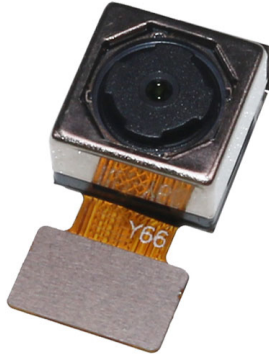
Specifications

Camera Module No.	YDS-OV5645-Y660B V3.1
Resolution	5MP
Image Sensor	OV5645
Sensor Type	1/4"
Pixel Size	1.4 um x 1.4 um
EFL	3.29 mm
F.NO	2.80
Pixel	2592 x 1944
View Angle	68.7°(DFOV) 58.1°(HFOV) 45.0°(VFOV)
Lens Dimensions	8.50 x 8.50 x 5.17 mm
Module Size	15.90 x 8.50 mm
Module Type	Auto Focus
Interface	MIPI
Auto Focus VCM Driver IC	Embedded
Lens Model	YDS-LENS-M5101
Lens Type	650nm IR Cut
Operating Temperature	-30°C to +70°C
Mating Connector	BBR43-24KB533



YDS-OV5645-Y660B V3.1

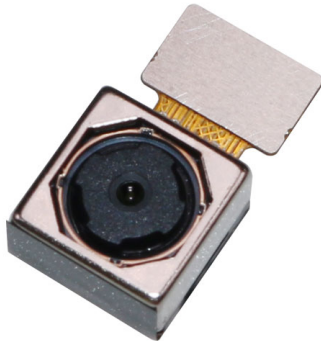
5MP OmniVision OV5645 MIPI Interface Auto Focus Camera Module



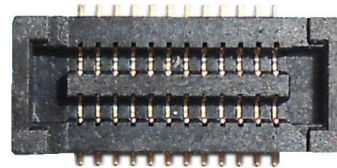
Top View



Side View



Bottom View

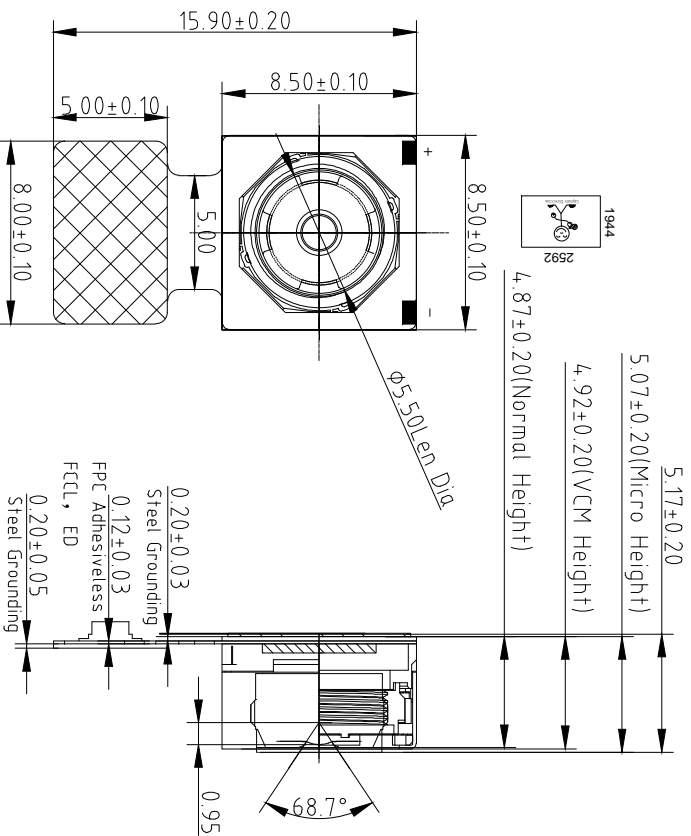


Mating Connector

ROHS

PIN NO	NAME
1	MCLK
2	PWDN
3	GND
4	DATAN0
5	DATAP0
6	CLKN
7	CLKP
8	GND
9	IOVDD(1.8V)
10	AVDD(2.8V)
11	GND
12	RESET
13	SCL
14	SDA
15	GND
16	DATAN1
17	DATAP1
18	AGND
19	NC
20	NC
21	NC
22	DVDD(1.5V)
23	AFVDD(2.8V)
24	NC

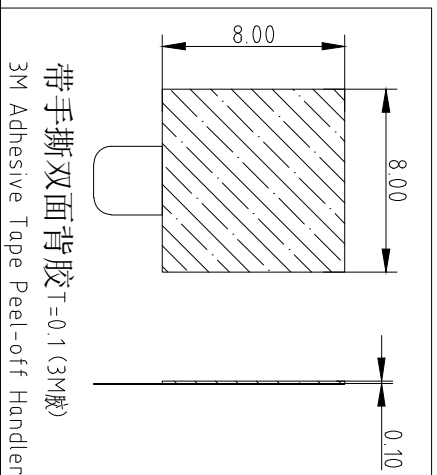
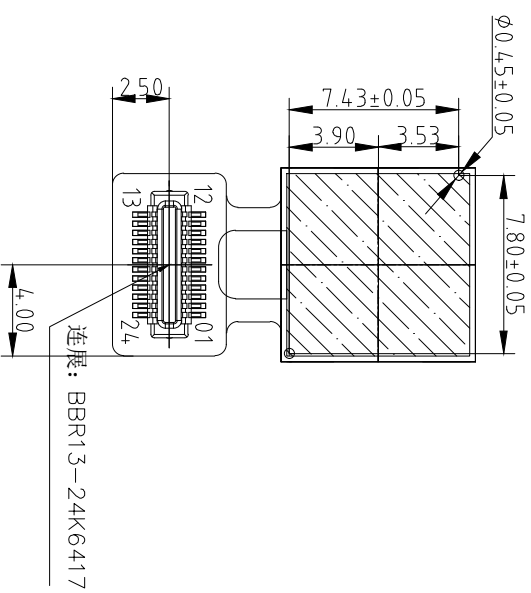
焦距 (EFL)	3.29
光圈 (F.NO)	2.8
视场角 (View Angle)	68.7°
畸变 (Distortion)	< 1%
镜头类型 (Lens Size)	1/4 inch
像素 (Array Size)	2592*1944
感光芯片 (Chip Type)	OV5645



TOP VIEW

SIDE VIEW

BOTTOM VIEW



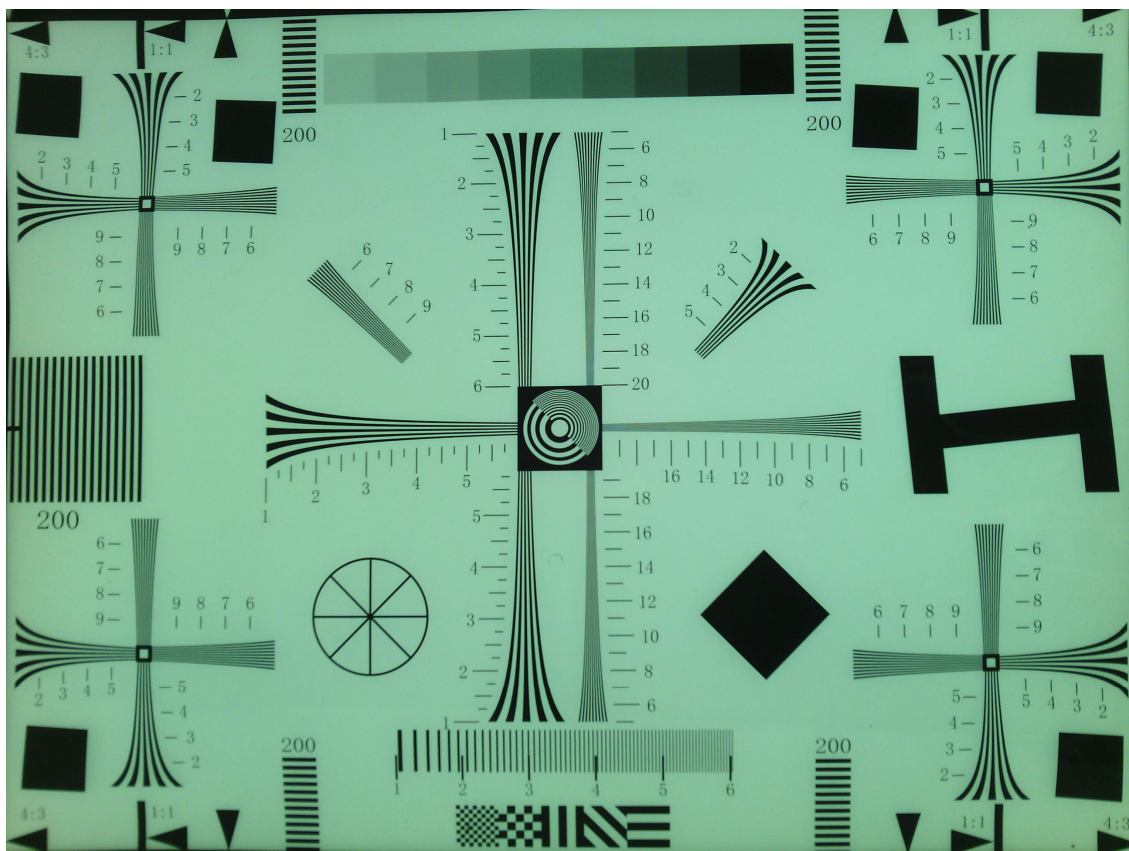
产品变更	详细变更事项
(1)	
(2)	
(3)	

1 / 0	All	First Release	Kevin	2017-08-11
REV.	Zone	Description	Approved	Date

Designed By:	Kevin	Client Name:	Y660
Checked By:	Feng Liu	Model Name:	OV5645-Y660B V3.1
Approved By:	Aouly_Yan	Projection Type:	Unit: mm
		Third Angle	Scale: 1:1
			Sheet: 1 of 1
			Version: 1/0

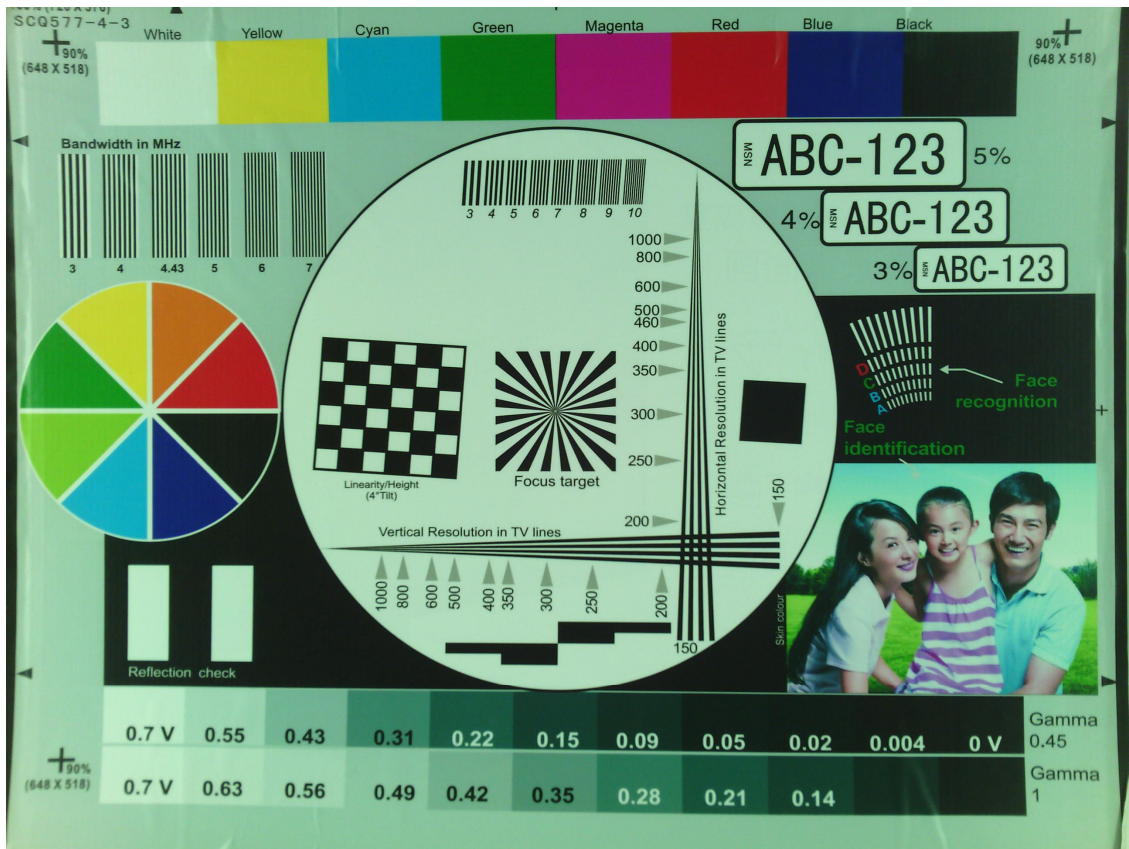
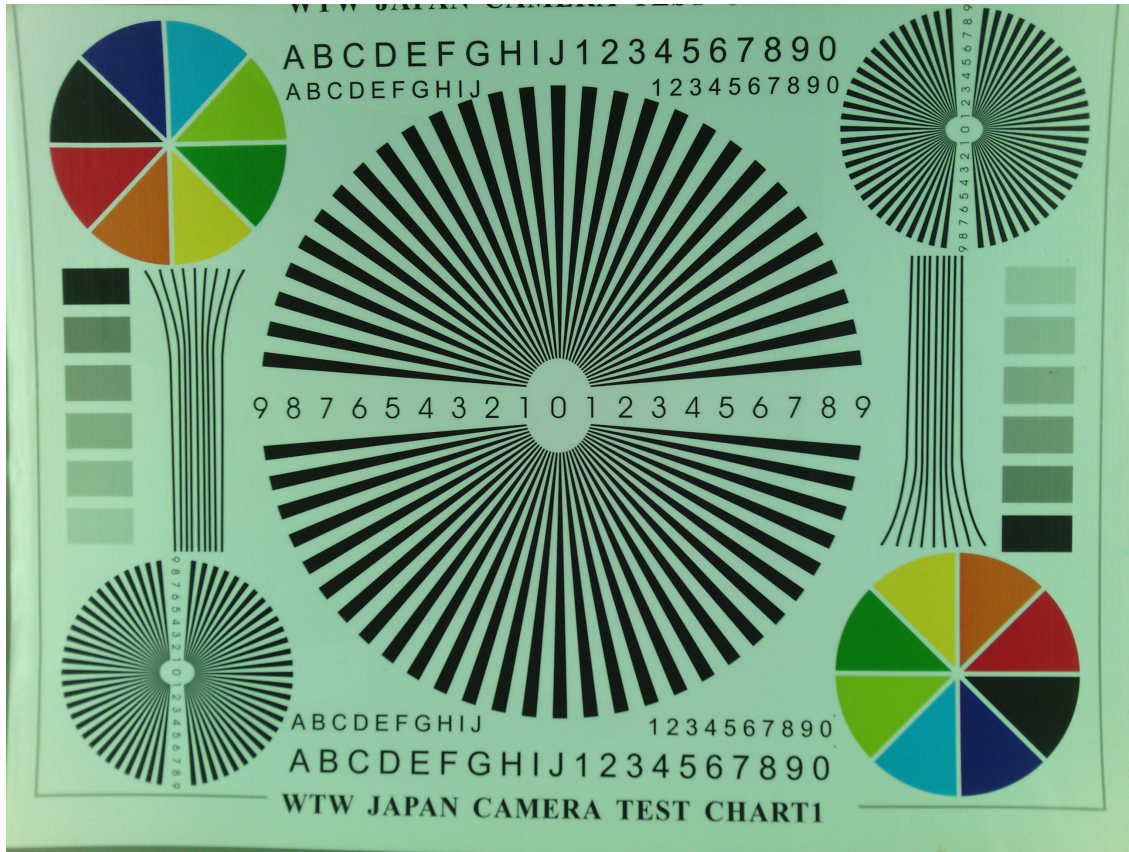
Real Test Images

OV5645-Y660B V3.1

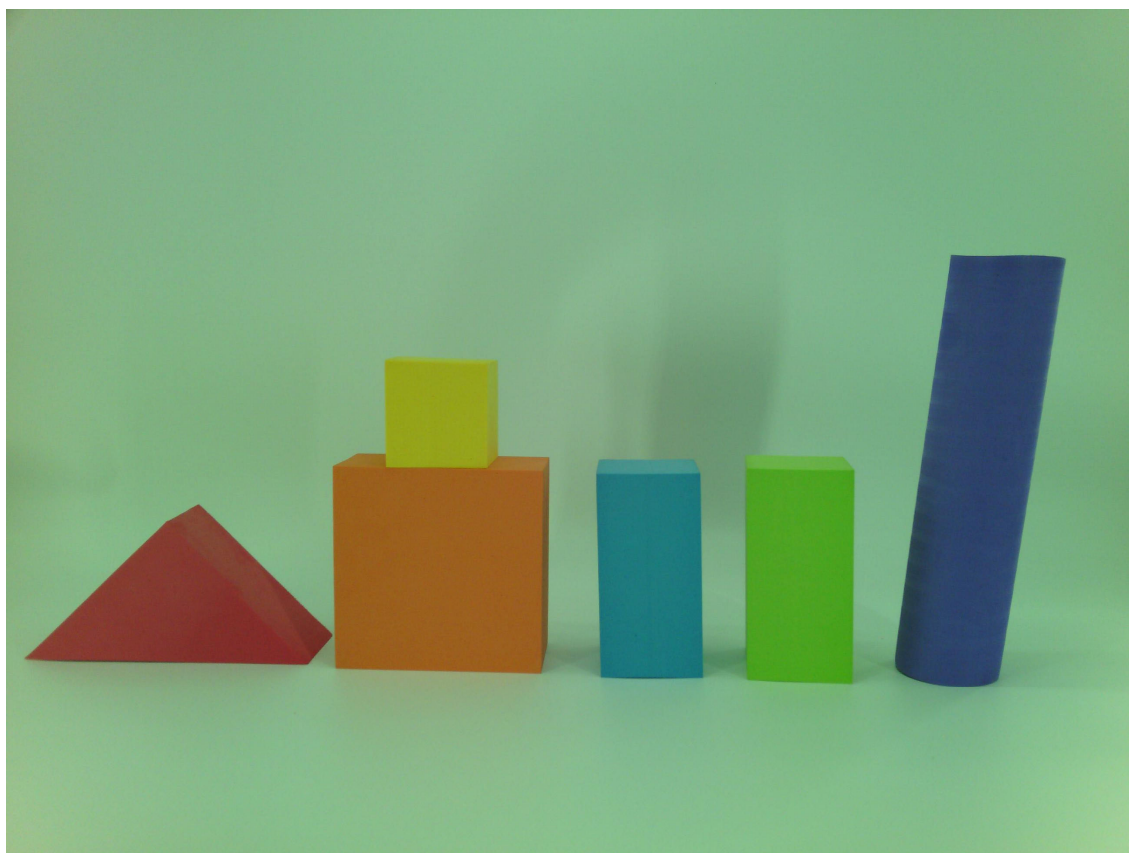


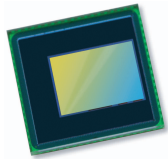
Real Test Images

OV5645-Y660B V3.1



Real Test Images
OV5645-Y660B V3.1





OV5645 5-megapixel product brief



High Quality 5-Megapixel Photography and HD Video for Low-Cost Mobile Devices



available in
a lead-free
package

OmniVision's OV5645 is a high performance, 5-megapixel system-on-chip (SOC) ideally suited for the cost-sensitive segment of the mobile handset market. The CameraChip™ sensor's single MIPI port replaces both a bandwidth-limited DVP interface and a costly embedded JPEG compressor, allowing the new OV5645 sensor to save significant silicon area and cost. An embedded autofocus control with voice coil motor driver offers further cost savings for the end user, making the OV5645 a highly attractive alternative to other 5-megapixel sensors currently on the market.

The OV5645 also features a new picture-in-picture (PIP) architecture that offers an easy-to-implement, low-cost dual camera system solution for mobile handsets and smartphones. The feature is based on a master/slave configuration where a front-facing camera (OV7965) can be connected through the OV5645 master camera, enabling a two-camera system with PIP functionality without the need for an additional MIPI interface into the baseband processor.

Built on OmniVision's 1.4-micron OmniBSI™ pixel architecture, the OV5645 offers high performance 5-megapixel photography and 720p HD video at 60 frames per second (FPS) and 1080p HD video at 30 FPS with complete user control over formatting and output data transfer. The sensor's 720p HD video is captured in full field-of-view with 2 x 2 binning, which doubles the sensitivity and improves the signal-to-noise ratio (SNR). A unique post-binning, re-sampling filter function removes zigzag artifacts around slant edges and minimizes spatial artifacts to deliver even sharper, crisper color images.

Find out more at www.ovt.com.

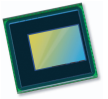
Applications

- Cellular Phones
- PC Multimedia
- Toys
- Digital Still Cameras

Product Features

- 1.4 μm x 1.4 μm pixel with OmniBSI+™ technology for high performance (high sensitivity, low crosstalk, low noise, improved quantum efficiency)
- optical size of 1/4"
- automatic image control functions: automatic exposure control (AEC), automatic white balance (AWB), automatic band filter (ABF), automatic 50/60 Hz luminance detection, and automatic blacklevel calibration (ABLC)
- image quality controls: color saturation, hue, gamma, sharpness (edge enhancement), lens correction, defective pixel canceling, and noise canceling
- support for output formats: RAW RGB, RGB565/555/444, YUV422/420, YCbCr422
- support for video or snapshot operations
- support for internal and external frame synchronization for frame exposure mode
- support for LED and flash strobe mode
- support for horizontal and vertical sub-sampling, binning
- support for minimizing artifacts on binned image
- support for data compression output
- support for anti-shake
- standard serial SCCB interface
- dual lane MIPI output interface
- embedded 1.5V regulator for core power
- programmable I/O drive capability, I/O tri-state configurability
- support for black sun cancellation
- support for images sizes: 5 megapixel, and any arbitrary size scaling down from 5 megapixel
- support for auto focus control (AFC) with embedded AF VCM driver
- embedded microcontroller
- suitable for module size of 8.5 x 8.5 x $\lt; 6\text{mm}$ with both CSP and RW packaging

OV5645



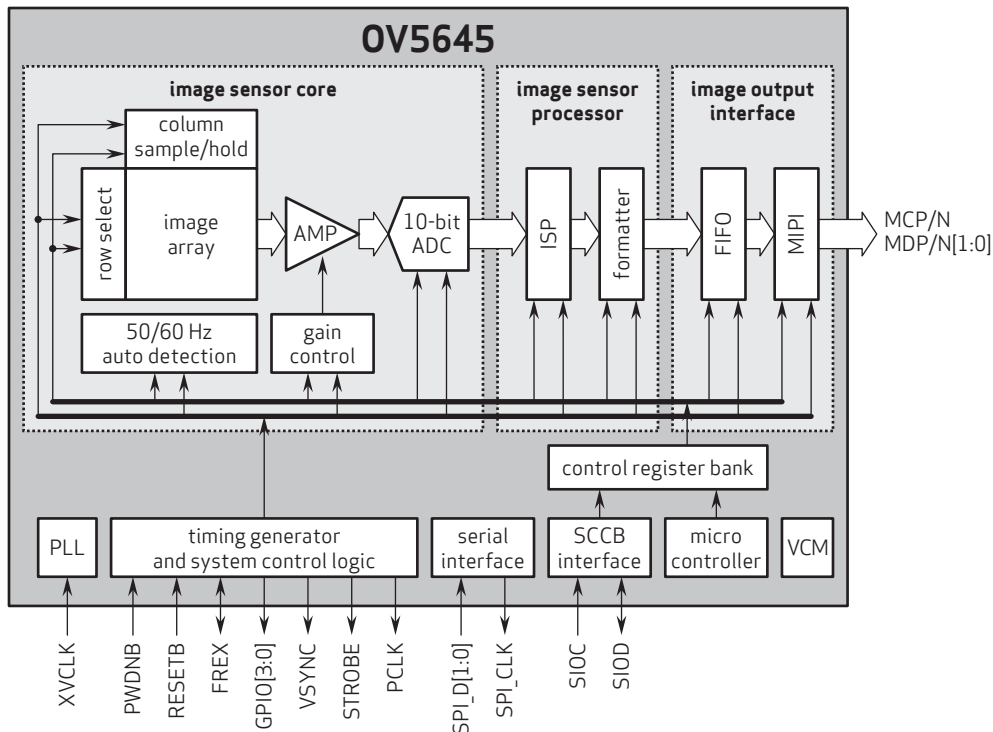
Ordering Information

- OV05645-A66A (color, lead-free, 66-pin CSP3)
- OV05645-G04A (color, chip probing, 200 μm backgrinding, reconstructed wafer)

Product Specifications

- active array size: 2592 x 1944
- power supply:
 - core: 1.5V $\pm 5\%$ (with embedded 1.5 regulator)
 - analog: 2.6 - 3.0V (2.8V typical)
 - I/O: 1.8V / 2.8V
- temperature range:
 - operating: -30°C to 70°C junction temperature
 - stable image: 0°C to 50°C junction temperature
- output formats: 8-/10-bit RGB RAW, RGB565/555/444, YUV422/420, YCbCr422 output
- lens size: 1/4"
- lens chief ray angle: 29.1°
- input clock frequency: 6 - 27 MHz
- max S/N ratio: 36 dB
- maximum image transfer rate:
 - QSXGA (2592X1944): 15 fps
 - 1080p: 30 fps
 - 1280x960: 45 fps
 - 720p: 60 fps
- shutter: rolling shutter / frame exposure
- maximum exposure interval: 1964 x t_{row}
- pixel size: 1.4 μm x 1.4 μm
- image area: 3673.6 μm x 2738.4 μm
- package/die dimensions:
 - CSP3: 6200 μm x 4860 μm
 - COB: 6190 μm x 4850 μm

Functional Block Diagram



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USA

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Fax: + 1 408 567 3001
www.ovt.com

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OmniVision

YDS-LENS-M5101

SPECIFICATION		
1. SENSOR SIZE	1/4" (5M CSP)	
2. MAX IMAGE CIRCLE	φ4.90mm	
3. TOTAL TRACK	4.18±0.1mm	
4. BFL	3.29mm	
5. OPTICAL BFL	1.43mm	
6. MECHANICAL BFL	0.85mm	
7. F/NO	2.8±5%	
8. VIEW OF FIELD	VERTICAL	45.0° (γ=1.36)
	HORIZONTAL	58.1° (γ=1.814)
	DIAGONL	68.7° (γ=2.268)
9. OPTICAL DISTORTION	<1.0%	
10. TV DISTORTION	<1.0%	
11. RELATIVE ILLUMINATION	>42.3%	
12. CONSTRUCTION	4F+IR FILTER	
13. CHIEF RAY ANGLE	<25°	
14. CUT FREQUENCY AT 50%	650±10nm	
15. THREAD	M6.0X0.35P	
16. IMAGE QUALITY	AXIS	330lp/mm
	0.7Y	200lp/mm
17. APPEARANCE QUALITY (Scratch/Di ₂)	CENTER	20/10
	EDGE	40/20

NO	MODIFY CONTENT	NAME	DATE	ANGLE	DIM	TYPE	UNIT	MATERIAL	SCALE	APPROVED BY	FINISH	DATE	LOCATION	REV
1									8 : 1			2013.05.03		A-00

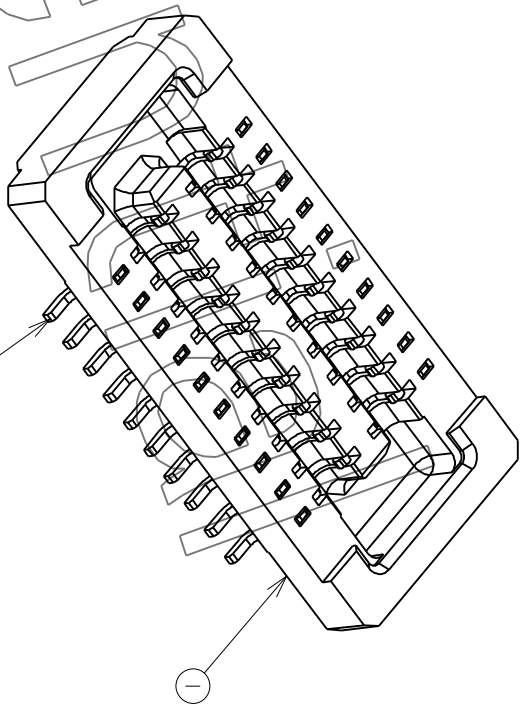
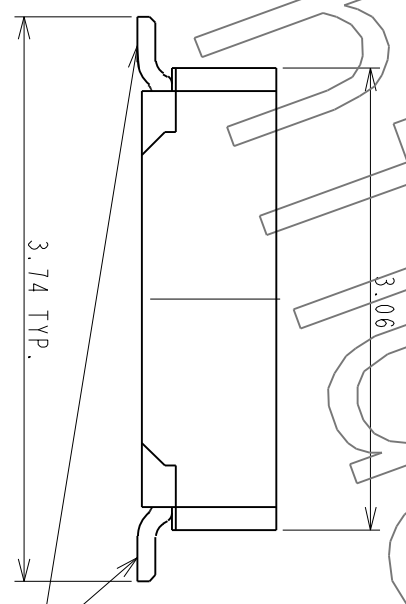
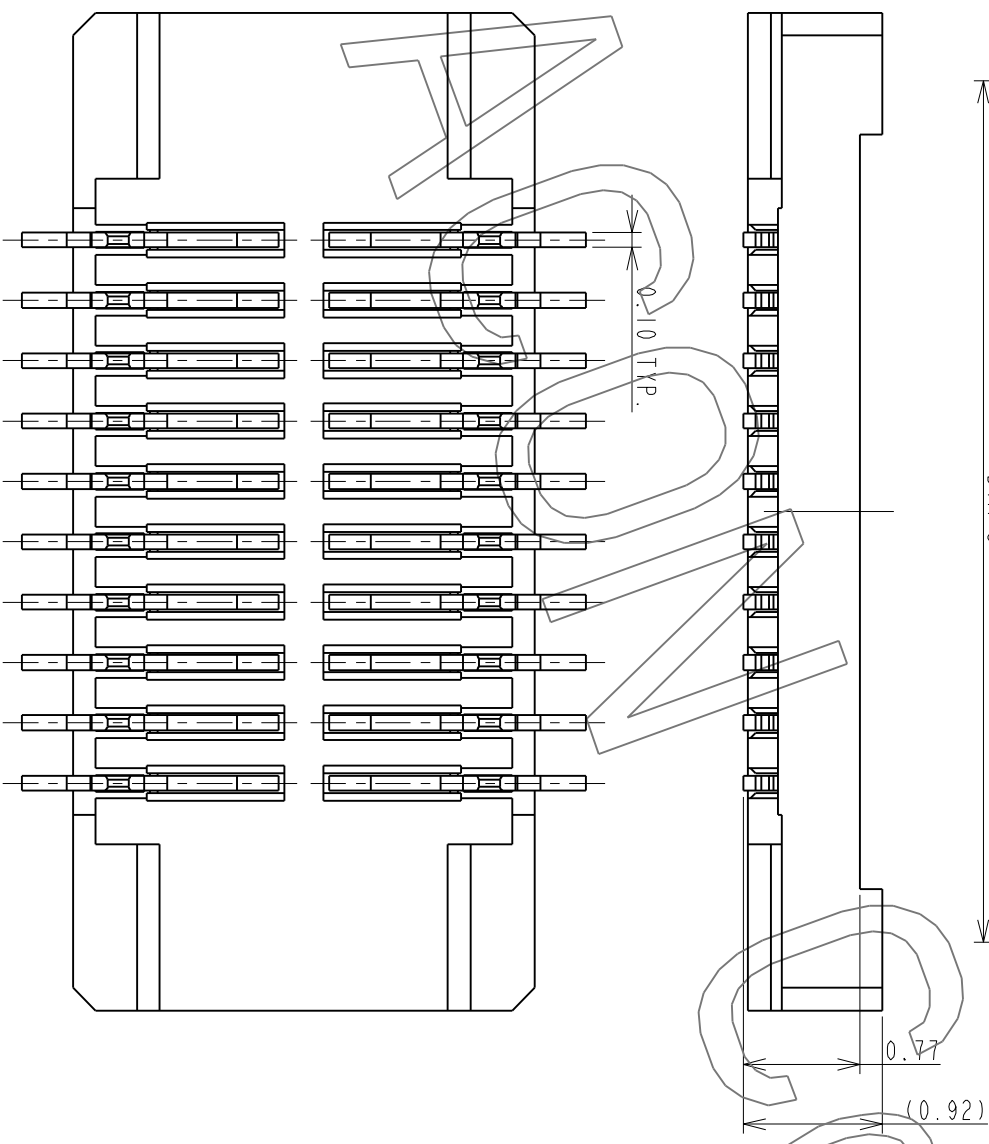
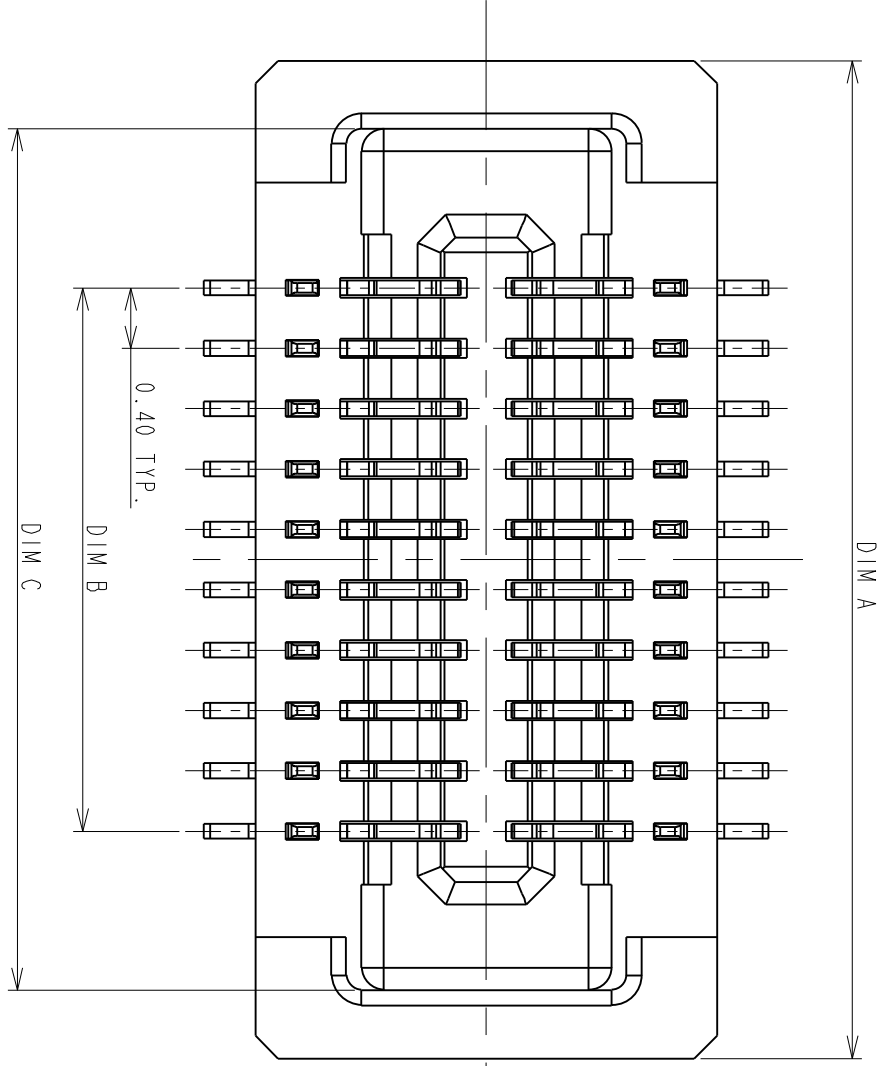
NOTE:

- 镜头表面不可有油污、灰尘、毛丝等异物。
- 镜头配VCM锁附高度为 4.7±0.1mm, 扭力为20—60gf.cm。
- 镜头承受推力为≥2.0kg。
- 镜头品质参数需符合图中要求。

The drawing shows a lens with a diameter of 5.40mm and a central hole of 4.7mm. The front view shows chamfered edges with R0.15 radii and 4-45 degree chamfers. The side view shows a total thickness of 4.18±0.10mm, with an optical BFL of 1.43mm and a mechanical BFL of 0.85mm. The lens is mounted on a base with a 6.0x0.35mm thread. The drawing also indicates an IR CUT filter and an IMAGE PLANE.

1 2 3 4 5 6 7 8

REV.	EC#	DESCRIPTION	DATE	DRAWN	CHECKED	APPROVED
A	TJECR10018-02	NEW RELEASE PER NPRI 0009	11/05/10'	RAIN	DICK, SON	HARDWARE
B	TJECR13014	AXI, AXI	05/13/13'	RAIN	SteveM	Jeff



0.08
ALL OF PLACES

ITEM	NAME	Q'TY	PART #	MATERIAL / FINISH
2	CONTACT	XX	T-BBR43-100X30	COPPER ALLOY/PLATING GOLD
1	HOUSING	1	I-BBR43-1XXX33	HIGH TEMP RESIN/UL 94 V-0

TOLERANCES UNLESS OTHERWISE SPECIFIED	
GENERAL	.XX ±0.38
DESIGN	.XXX ±0.25
RAIN	04/15/10'
CHECKED	DATE
HARDWARE	04/24/10'
APPROVED	DATE
DICK, LEE	04/24/10'



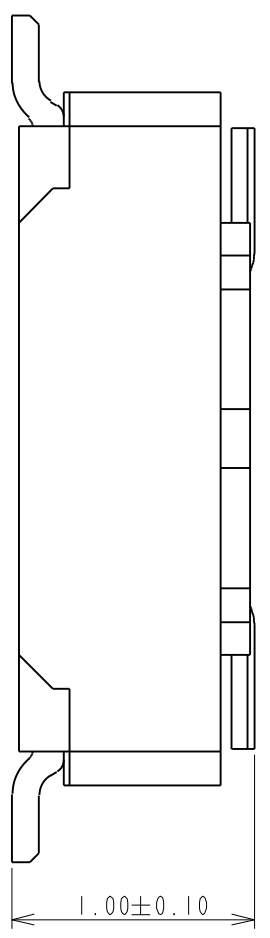
P0.4#11.0mm BOARD TO BOARD
CONN. RECEPTACLE
WITHOUT HOLD DOWN

SCALE	SHEET	UNIT	TITLE	SERIES	DWG NO.	REV.
20:1	1 OF 2	MM	CUSTOMER DRAWING	BBR	C-BBR43-04-01	B

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All materials meet the ACON's spec. environment-related substances management technical standard

F E D C B A



PRODUCT NUMBERING CODE:
 BBR43 - XX K X 5 X X
 1 2 3 4 5 6 7

1. PRODUCTION CODE:
 BBR43: BOARD TO BOARD 0.4 PITCH RECEPTACLE

2. POSITIONS:
 XX: POSITIONS(SEE TABLE A)

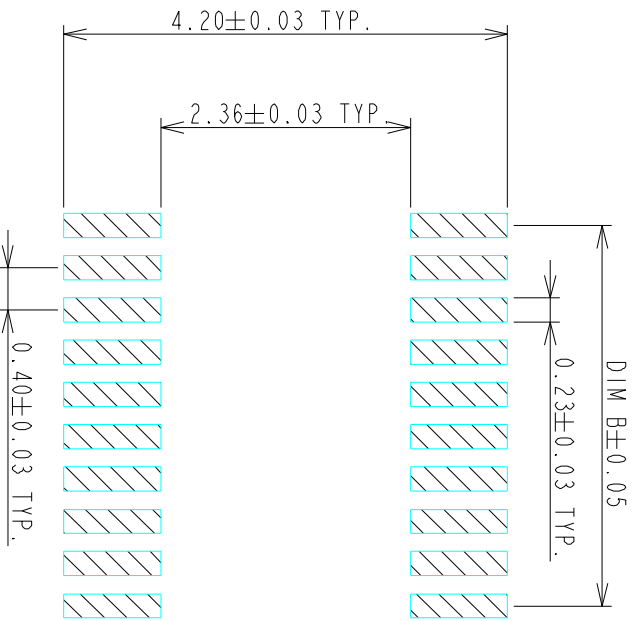
3. INSULATOR COLOR:
 K: BLACK

4. CONTACT PLATING:
 1: GOLD 10u" MIN
 2: GOLD 5u" MIN
 3: GOLD 10u" MIN
 B: GOLD 4u" MIN FOR SPOT PLATING
 ALL OVER: NI 50~100u"

5. TYPE OF HEIGHT:
 5: H=0.77mm

6. TYPE OF HOLD DOWN:
 3: WITHOUT HOLD DOWN

7. OTHER
 2: WITH POST, FINISHED PRODUCTS
 3: WITHOUT POST, FINISHED PRODUCTS



RECOMMENDED P.C. BOARD PATTERN DIMENSION (WITHOUT HOLD DOWN)

NOTES:
 1.0: RATING:
 1.1: VOLTAGE: 60V AC/DC
 1.2: CURRENT: 0.5 AMPS
 1.3: OPERATION TEMPERATURE: -40°C TO +85°C
 2.0: ELECTRICAL CHARACTERISTIC:
 2.1: CONTACT RESISTANCE: 50 mΩ MAX INITIAL
 2.2: INSULATION RESISTANCE: 1000 MΩ MIN INITIAL
 2.3: DIELECTRIC WITHSTANDING VOLTAGE: 250V AC FOR ONE MINUTE
 3.0 TOLERANCES UNLESS OTHERWISE SPECIFIED
 GENERAL: DIMENSION >10.00 ±0.13
 DIMENSION 5.00~10.00 ±0.10
 DIMENSION <5.00 ±0.05

4.0 ALL COPPLANARITY IS 0.08mm MAX. BEFORE REFLOW
 ALL COPPLANARITY IS 0.10mm MAX. AFTER REFLOW

TABLE A:

POSITIONS	DIM A	DIM B	DIM C
10	4.61	1.60	3.71
14	5.41	2.40	4.51
16	5.81	2.80	4.91
18	6.21	3.20	5.31
20	6.61	3.60	5.71
22	7.01	4.00	6.11
24	7.41	4.40	6.51
26	7.81	4.80	6.91
30	8.61	5.60	7.71
32	9.01	6.00	8.11
34	9.41	6.40	8.51
40	10.61	7.60	9.71
44	11.41	8.4	10.51
48	12.21	9.20	11.31
50	12.61	9.60	11.71
54	13.41	10.40	12.51
60	14.61	11.60	13.71
70	16.61	13.60	15.71
80	18.61	15.60	17.71

TOLERANCES UNLESS OTHERWISE SPECIFIED		DRAWN		DATE	
GENERAL X	±0.38	RAIN	04/15/10		
XX	±0.13	DESIGN			
XXX	±0.05	RAIN	04/15/10		
ANGLES X°	±3.0°	CHECKED			
Y°	±2.0°	HARDWARE	04/24/10		
Z°	±1.0°	APPROVED			
SCALE 20:1		DICK. LEE	04/24/10		
SHEET 2 OF 2		DATE		TITLE	
UNIT MM		DATE		P0.4*H1.0mm BOARD TO BOARD	
		DATE		CONN. RECEPTACLE	
		DATE		WITHOUT HOLD DOWN	
		DATE		ADVANCED-CONNECTEK INC.	
		DATE		SERIES BBR	
		DATE		DWG NO. C-BBR43-04-01	
		DATE		SIZE A3	
		DATE		REV. B	



YDS CAMERA MODULE

your best camera partner

Camera Module Pinout Definition Reference Chart

OmniVision	Sony	Samsung	On-Semi	Aptina	Himax	GalaxyCore	PixArt	SmartSens	Sensors
Pin Signal		Description							
DGND	GND	ground for digital circuit							
AGND		ground for analog circuit							
PCLK	DCK	DVP PCLK output							
XCLR	PWDN	XSHUTDOWN	STANDBY	power down active high with internal pull-down resistor					
MCLK	XVCLK	XCLK	INCK	system input clock					
RESET	RST	reset active low with internal pull-up resistor							
NC	NULL	no connect							
SDA	SIO_D	SIOD	SCCB data						
SCL	SIO_C	SIOC	SCCB input clock						
VSYNC	XVS	FSYNC	DVP VSYNC output						
HREF	XHS	DVP HREF output							
DOVDD	power for I/O circuit								
AFVDD	power for VCM circuit								
AVDD	power for analog circuit								
DVDD	power for digital circuit								
STROBE	FSTROBE	strobe output							
FSIN	synchronize the VSYNC signal from the other sensor								
SID	SCCB last bit ID input								
ILPWM	mechanical shutter output indicator								
FREX	frame exposure / mechanical shutter								
GPIO	general purpose inputs								
SLASEL	I2C slave address select								
AFEN	CEN chip enable active high on VCM driver IC								
MIPI Interface									
MDN0	DN0	MD0N	DATA_N	DMO1N	MIPI 1st data lane negative output				
MDP0	DP0	MD0P	DATA_P	DMO1P	MIPI 1st data lane positive output				
MDN1	DN1	MD1N	DATA2_N	DMO2N	MIPI 2nd data lane negative output				
MDP1	DP1	MD1P	DATA2_P	DMO2P	MIPI 2nd data lane positive output				
MDN2	DN2	MD2N	DATA3_N	DMO3N	MIPI 3rd data lane negative output				
MDP2	DP2	MD2P	DATA3_P	DMO3P	MIPI 3rd data lane positive output				
MDN3	DN3	MD3N	DATA4_N	DMO4N	MIPI 4th data lane negative output				
MDP3	DP3	MD3P	DATA4_P	DMO4P	MIPI 4th data lane positive output				
MCN	CLKN	CLK_N	DCKN	MIPI clock negative output					
MCP	CLKP	MCP	CLK_P	DCKN	MIPI clock positive output				
DVP Parallel Interface									
D0	DO0	Y0	DVP data output port 0						
D1	DO1	Y1	DVP data output port 1						
D2	DO2	Y2	DVP data output port 2						
D3	DO3	Y3	DVP data output port 3						
D4	DO4	Y4	DVP data output port 4						
D5	DO5	Y5	DVP data output port 5						
D6	DO6	Y6	DVP data output port 6						
D7	DO7	Y7	DVP data output port 7						
D8	DO8	Y8	DVP data output port 8						
D9	DO9	Y9	DVP data output port 9						
D10	DO10	Y10	DVP data output port 10						
D11	DO11	Y11	DVP data output port 11						

www.YDSCAM.com sales@ydscam.com Phone (WeChat, QQ): (+86) 177 2732 6718

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Cameras Applications



IMAGING DEVICES



Camera Reliability Test

Reliability Inspection Item		Testing Method	Acceptance Criteria	
Category	Item			
Environmental	Storage Temperature	High 60°C 96 Hours	Temperature Chamber	No Abnormal Situation
		Low -20°C 96 Hours	Temperature Chamber	No Abnormal Situation
	Operation Temperature	High 60°C 24 Hours	Temperature Chamber	No Abnormal Situation
		Low -20°C 24 Hours	Temperature Chamber	No Abnormal Situation
	Humidity	60°C 80% 24 Hours	Temperature Chamber	No Abnormal Situation
	Thermal Shock	High 60°C 0.5 Hours Low -20°C 0.5 Hours Cycling in 24 Hours	Temperature Chamber	No Abnormal Situation
Physical	Drop Test (Free Falling)	Without Package 60cm	10 Times on Wood Floor	Electrically Functional
		With Package 60cm	10 Times on Wood Floor	Electrically Functional
	Vibration Test	50Hz X-Axis 2mm 30min	Vibration Table	Electrically Functional
		50Hz Y-Axis 2mm 30min	Vibration Table	Electrically Functional
		50Hz Z-Axis 2mm 30min	Vibration Table	Electrically Functional
	Cable Tensile Strength Test	Loading Weight 4 kg 60 Seconds Cycling in 24 Hours	Tensile Testing Machine	Electrically Functional
Electrical	ESD Test	Contact Discharge 2 KV	ESD Testing Machine	Electrically Functional
		Air Discharge 4 KV	ESD Testing Machine	Electrically Functional
	Aging Test	On/Off 30 Seconds Cycling in 24 Hours	Power Switch	Electrically Functional
	USB Connector	On/Off 250 Times	Plug and Unplug	Electrically Functional



Camera Inspection Standard

Inspection Item		Inspection Method	Standard of Inspection		
Category	Item				
Appearance	FPC/ PCB	Color	The Naked Eye	Major Difference is Not Allowed.	
		Be Torn/Chopped	The Naked Eye	Copper Crack Exposure is Not Allowed.	
		Marking	The Naked Eye	Clear, Recognizable (Within 30cm Distance)	
	Holder	Scratches	The Naked Eye	The Inside Crack Exposure is Not Allowed	
		Gap	The Naked Eye	Meet the Height Standard	
		Screw	The Naked Eye	Make Sure Screws Are Presented (If Any)	
		Damage	The Naked Eye	The Inside Crack Exposure is Not Allowed	
	Lens	Scratch	The Naked Eye	No Effect On Resolution Standard	
		Contamination	The Naked Eye	No Effect On Resolution Standard	
		Oil Film	The Naked Eye	No Effect On Resolution Standard	
		Cover Tape	The Naked Eye	No Issue On Appearance.	
	Function	Image	No Communication	Test Board	Not Allowed
			Bright Pixel	Black Board	Not Allowed In the Image Center
Dark Pixel			White board	Not Allowed In the Image Center	
Blurry			The Naked Eye	Not Allowed	
No Image			The Naked Eye	Not Allowed	
Vertical Line			The Naked Eye	Not Allowed	
Horizontal Line			The Naked Eye	Not Allowed	
Light Leakage			The Naked Eye	Not Allowed	
Blinking Image			The Naked Eye	Not Allowed	
Bruise			Inspection Jig	Not Allowed	
Resolution			Chart	Follows Outgoing Inspection Chart Standard	
Color			The Naked Eye	No Issue	
Noise			The Naked Eye	Not Allowed	
Corner Dark			The Naked Eye	Less Than 100px By 100px	
Color Resolution			The Naked Eye	No Issue	
Dimension	Height	The Naked Eye	Follows Approval Data Sheet		
	Width	The Naked Eye	Follows Approval Data Sheet		
	Length	The Naked Eye	Follows Approval Data Sheet		
	Overall	The Naked Eye	Follows Approval Data Sheet		

YDSCAM Package Solutions

YDS Camera Module



Complete with Lens Protection Film



Tray with Grid and Space

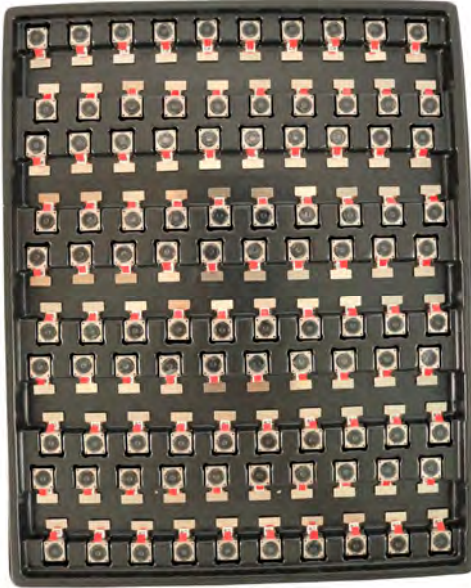


Place Cameras on the Tray

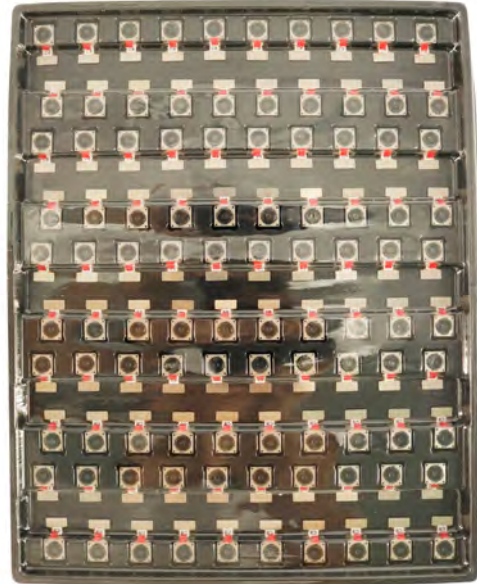


YDSCAM Package Solutions

Full Tray of Cameras



Cover Tray with Lid



Place Tray into Anti-Static Bag



Vacuum the Anti-Static Bag



YDSCAM Package Solutions

Sealed Vacuum Anti-Static Bag with Labels

1. Model and Description 2. Quantity 3. Manufacturing Date Code 4. Caution



YDSCAM Package Solutions

Place Foam Sheets Between Tray Bags



Foam Sheets are Larger Than Trays



Place Foam Sheets and Trays into Box



Foam Sheets are Tightly Fitting in Box



Seal the Carbon Box



Label the Carbon Shipping Box





YDSCAM Package Solutions

USB Camera Module

Complete with Lens Protection Film



Place Camera Sample into Anti-Static Bag

Place USB Cameras into Tray



Seal the Tray with Anti-Static Bag

Label the Carbon Shipping Box



YDSCAM Package Solutions

Place Camera Sample into Anti-Static Bag



Place Connectors into Anti-Static Bag



Label the Sample Bags



Place Connectors into Reel



Place Samples into the Carbon Box



Place Connectors into the Carbon Box





YDS CAMERA MODULE

your best camera partner

Company YDSCAM

YingDeShun Co. Ltd. (YDS) was established in 2017, a next-generation technology driven manufacturer specialized in research, design, and produce of audio and video products. YDS is occupying 20,000 square feet automated plants with 100 employees of annual throughput 30,000,000 units cameras.

YDS provides OEM, ODM design, contract manufacturing, and builds the camera products. You may provide the requirements to us, even with a hand draft, our sales and engineering work together to meet your needs. We consider ourselves your last-term partner in developing practical and innovative solutions.

Our team covers everything from initial concept development to mass produced product. YDS specializes in customized camera design, raw material, electronic engineering, firmware/software development, product testing, and packing design. Our experienced strategic supply systems offer a robust and dependable manufacturing capacity for orders of various sizes.



Limited Warranty

YDS provides the following limited warranty if you purchased the Product(s) directly from YDS company or from YDS's website www.YDSCAM.com. Product(s) purchased from other sellers or sources are not covered by this Limited Warranty. YDS guarantees that the Product(s) will be free from defects in materials and workmanship under normal use for a period of one (1) year from the date you receive the product ("Warranty Period").

For all Product(s) that contain or develop material defects in materials or workmanship during the Warranty Period, YDS will, at its sole option, either: (i) repair the Product(s); (ii) replace the Product(s) with a new or refurbished Product(s) (replacement Product(s) being of identical model or functional equivalent); or (iii) provide you a refund of the price you paid for the Product(s).

This Limited Warranty of YDS is solely limited to repair and/or replacement on the terms set forth above. YDS is not reliable or responsible for any subsequent events.



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YDS CAMERA MODULE

your best camera partner

YDS Strength

Powerful Factory



Professional Service



Promised Delivery



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